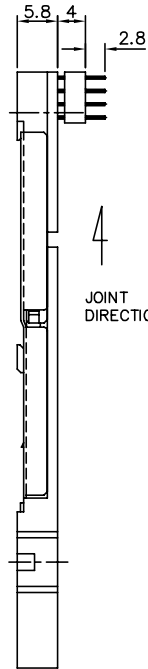
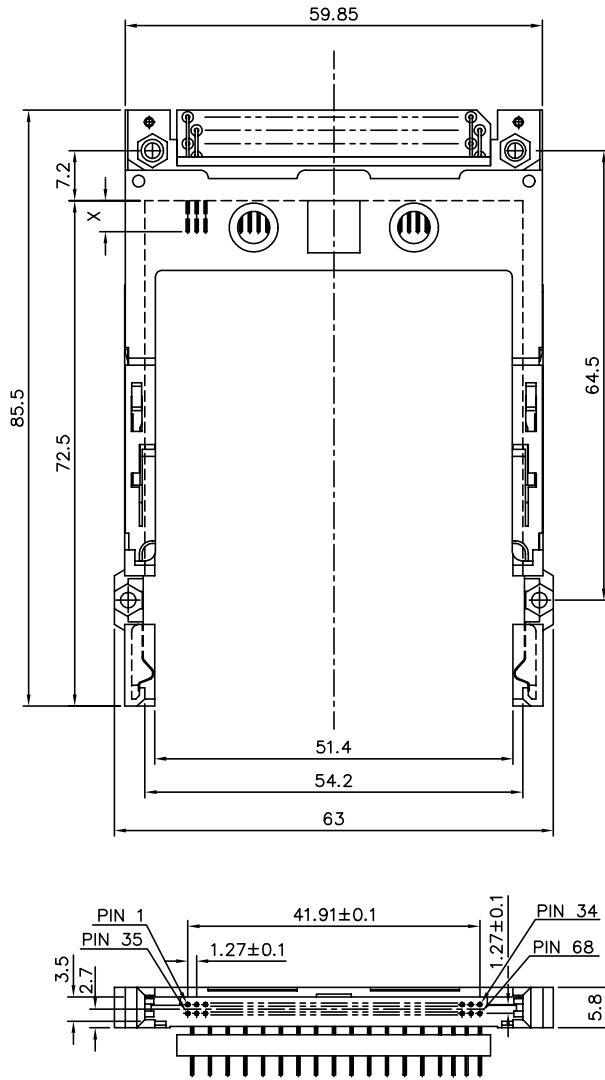


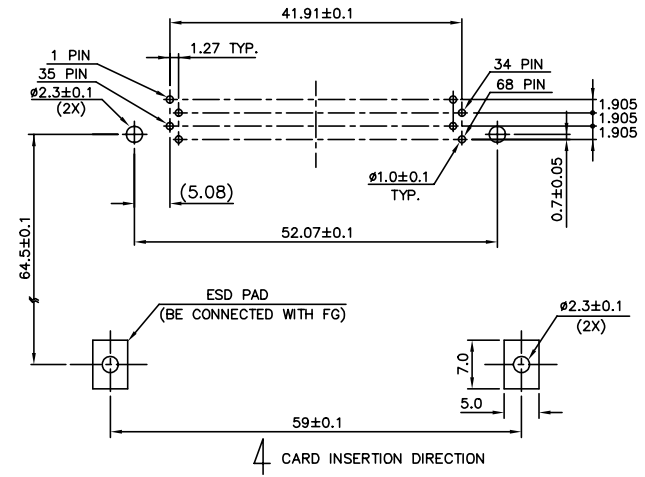
PRODUCT NO.
74500-040
74500-040LF



NOTES:

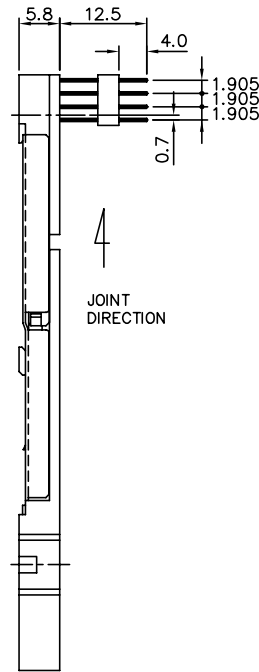
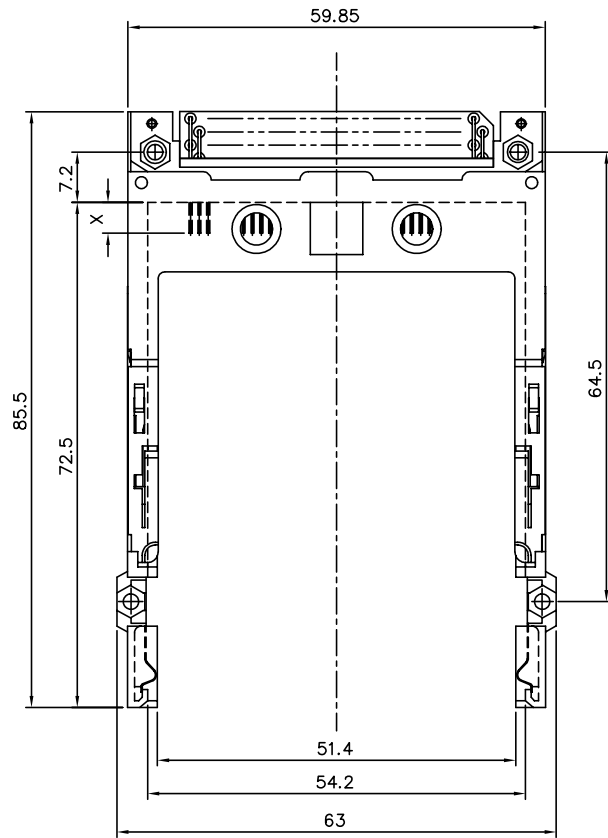
1. EJECT FORCE : 3.5 Kg MAX.
2. EJECT TRAVEL: 8.0mm
3. MATERIAL
  - 3.1 HEADER ASS'Y :
    - HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
    - PIN : COPPER ALLOY
  - 3.2 EJECT MECHANISM ASS'Y :
    - HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
    - PLATE : STAINLESS
    - EMI CONTACT: PHOSPHOR BRONZE
4. FINISH (PIN)
  - UNDER PLATING : 0.5µm MIN. Ni
  - CONTACT AREA : 0.076 µm MIN. GOLD
- SOLDER TAIL : 2.5µm MIN. Sn-Pb(FOR TIN LEAD OPTION)  
: 2.5µm MIN. PURE TIN (FOR LEAD FREE OPTION)
5.
 

DIM"x"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
6. IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER 260°C APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
7. IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
8. LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
9. PRODUCT SPEC: 110-263



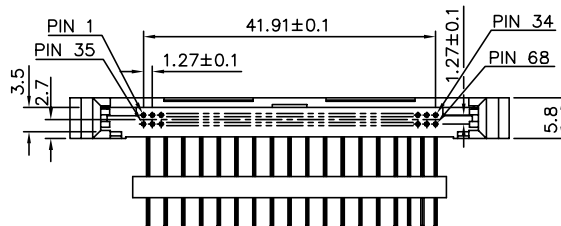
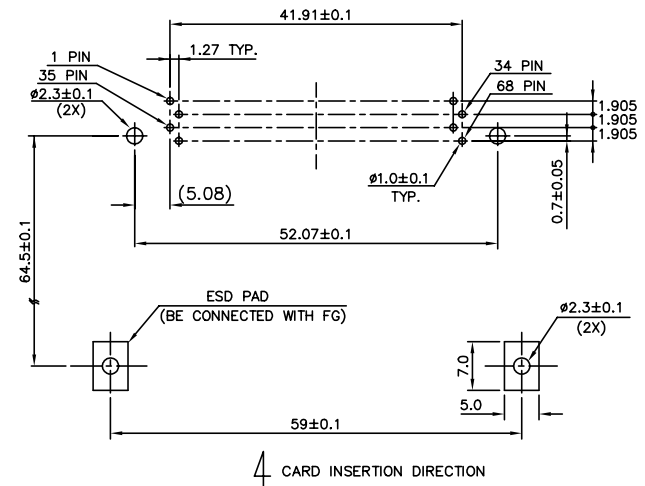
mat'l. code	surface ISO1302	tolerance ISO406 ISO1101	projection MM	product family PCMCIA
l'tecn nodr	date	tolerances unless other wise specified	scale: 6:1	title
A T70405	WL 0923/97	0.X±0.3	MM	EJECTOR HEADER ASS'Y 68POS. R/A TYP 1/2/3
B T80096	WL 02/17/98	0.XX±0.13		
C T03-0326	WL 08/14/03	0.XXX±0.05		
D N05-0127	WB 05/11/05	dr WENDY.CHEN 07/30/97		dwg no
E ELX-N-007947	ZK 11/01/11	engr JOSEPH HSIA 07/30/97	FCI	sheet 1 of 2
F ELX-N-011420	ZK 04/07/12	chr JOSEPH HSIA 07/30/97		74500
		appd JENN TSAO 07/30/97		type Product Customer Drawing
sheet index	revision sheet	F 1	F 2	

PRODUCT NO.
74500-000
74500-000LF



NOTES:

- MATERIAL
  - HEADER ASS'Y : HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK  
PIN : COPPER ALLOY
  - EJECT MECHANISM ASS'Y : HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK  
PLATE : STAINLESS  
EMI CONTACT: PHOSPHOR BRONZE
- FINISH (PIN)
  - UNDER PLATING : 0.5µm MIN. Ni
  - CONTACT AREA : 0.076 µm MIN. GOLD
  - SOLDER TAIL : 2.5µm MIN. Sn-Pb(FOR TIN LEAD OPTION)  
: 2.5µm MIN. PURE TIN (FOR LEAD FREE OPTION)
- | DIM"X"     | 4.25±0.1 | 3.5±0.1 | 5.0±0.1          |
|------------|----------|---------|------------------|
| PIN NUMBER | OTHERS   | 36,67   | 1,17,34,35,51,68 |
- IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER 260°C APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT APEC: 110-263



mat'l. code	surface ISD302 ✓	tolerance ISD406 ISD1101	projection MM	product family PCMCIA
l trechn nodr date	tolerances unless otherw	scale: 6:1	title EJECTOR HEADER ASS'Y 68POS. R/A TYP 1/2/3	
F	angle 0°±2'	0.X±0.3 0.XX±0.13 0.XXX±0.05	MM	sheet 2 of 2
	dr WENDY.CHEN 07/30/97	engr JOSPH HSIA 07/30/97	FCI	size A4
	chr JOSEPH HSIA 07/30/97	appd JENN TSAO 07/30/97	74500	
sheet index	revision sheet		type Product Customer Drawing	